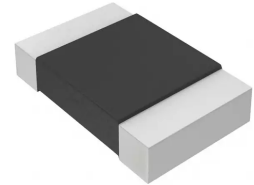
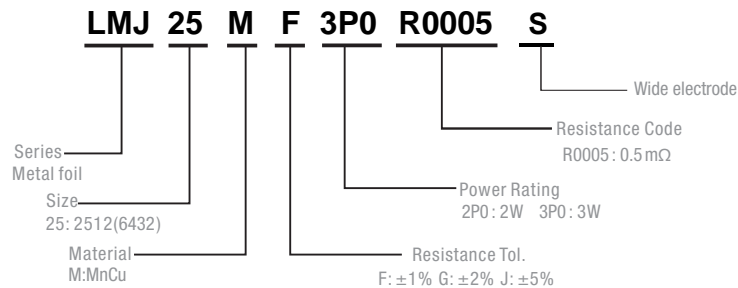


Description

- Proprietary processing technique produces extremely low resistance values
- Very low inductance
- Low thermal EMF
- Metallic Material



Part Numbering System

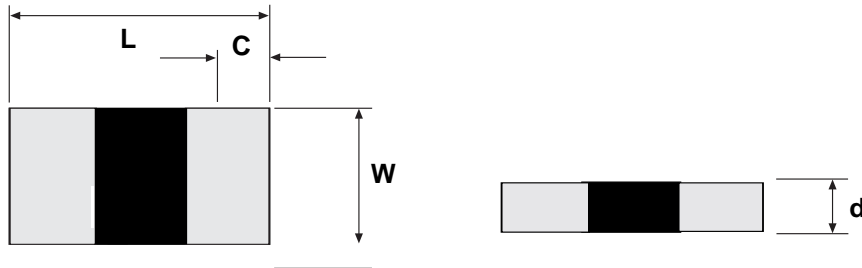


Parameter	Standard
Power Rating	2~3W
Resistance Value	0.5~0.75mΩ
Operating Temperature Range	-55 to +170°C
Component Temperature Coefficient (TCR)	± 50 ppm/°C
Maximum Working Voltage (V)	$(P \times R)^{1/2}$

Standard Electrical Specifications

Type	Rating Power at 70°C	T.C.R. (ppm/°C)	Resistance Range(mΩ) ±0.5% (D) ±1.0% (F) ±2.0% (G) ±5.0% (J)	Material	Electrode	Operating Temperature(°C)
LMJ25	3W	50	0.5	MnCu	Wide	-55~+170°C
	2W	50	0.75			

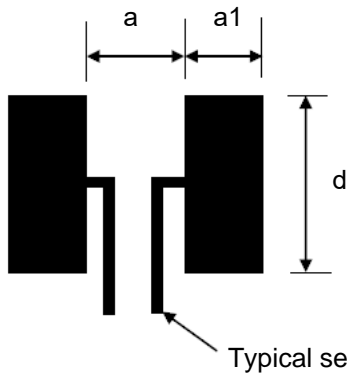
Construction



Unit: Millimeters

Style	Resistance (Ω)	L	W	C	d	Material
LMJ25	0.0005	6.4±0.2	3.2±0.2	2.5±0.2	0.9 ±0.20	MnCu
	0.00075	6.4±0.2	3.2±0.2	2.75±0.2	0.9 ±0.20	

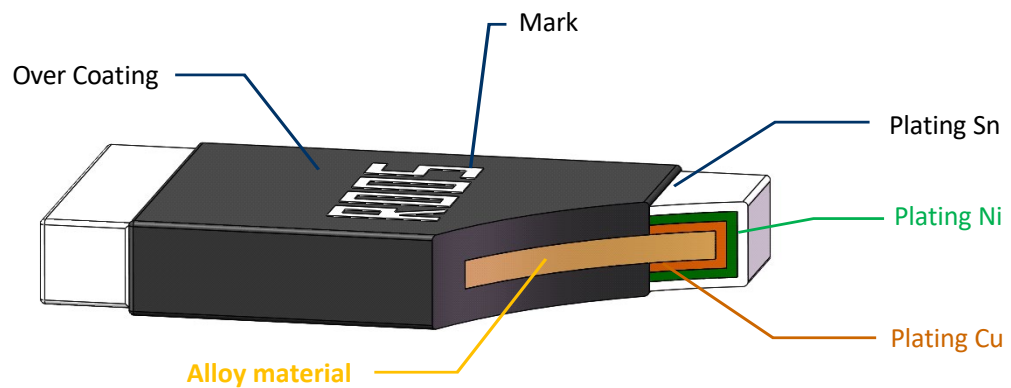
Recommended land pattern



Unit: Millimeters

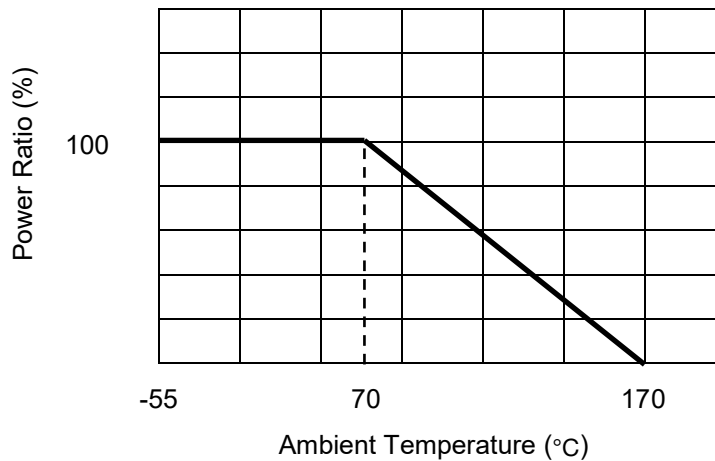
Resistance Range (Ω)	a	a1	d
0.0005~0.00075	1.3±0.1	3.1±0.1	4.0±0.1

Product structure diagram

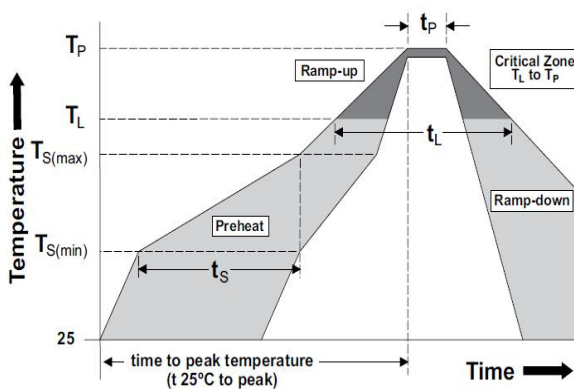


Power Derating Curve

For resistors operated in ambient temperatures 70°C, power rating shall be derated in accordance with the curve below:



Recommended Solder Curve

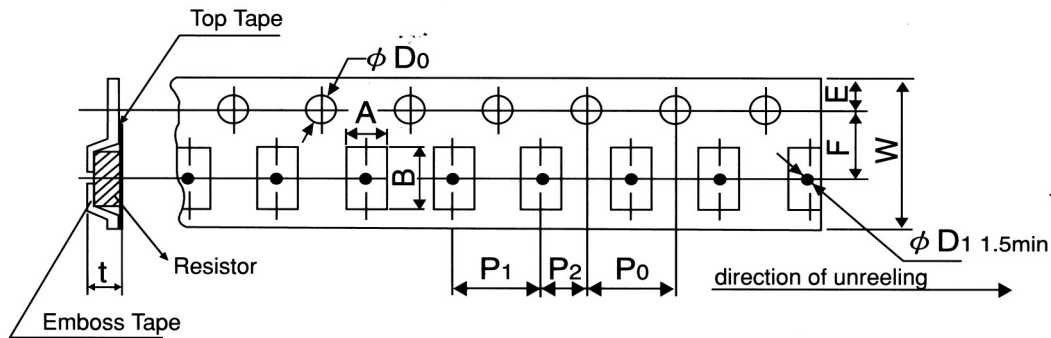


Reflow Condition		Pb – Free assembly
Pre heat	- Temperature Min (TS(min))	150°C
	- Temperature Max (TS(max))	200°C
	- Time (Min to Max) (ts)	60 – 120 secs
Average ramp up rate (Liquidus Temp (TL) to peak)		5°C/second max
TS(max) to TL - Ramp-up Rate		5°C/second max
Reflow	- Temperature (TL) (Liquidus)	217°C
	- Temperature (tL)	60 – 150 seconds
Peak Temperature (TP)		260°C
Time within 5°C of actual peak Temperature (tp)		20 – 40 seconds
Ramp-down Rate		5°C/second max
Time 25°C to peak Temperature (TP)		8 minutes Max.
Wave Soldering		260°C, 10 seconds max.
Hand Soldering		350°C, 5 seconds max.

Product Characteristics

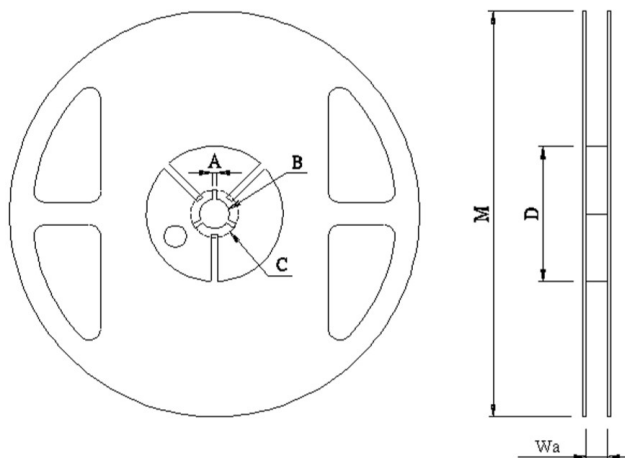
Item	Test condition/ Methods	Limited	Standard
Resistance	Measuring resistance value at room temperature 25°C±5°C	Refer to Spec	IEC60115-1 4.5
Temperature coefficient of resistance	$TCR = \frac{R - R_0}{R_0(T_2 - T_1)} \times 10^6$ R ₀ : resistance of room temperature R: resistance of 125°C T ₁ : Room temperature T ₂ : Temperature at 125°C	Refer to Spec	MIL-STD-202 Method 304
Short time Overload	Apply overload for 5 seconds and measure the resistance change rate after standing for 24 hours. 5 times the rated power for 5 seconds	≤±0.5%	MIL-R-26E
Resistance to Soldering Heat	260°C± 5°C time: 10sec± 1sec	≤±0.5%	MIL-STD-202 Method 210
Temperature Cycling	-55°C (15min)/+125°C(15min), 1000 cycles	≤±1%	MIL-STD-202 Method107G
Low temperature Storage	-55°C for 1000hours, No power	≤±0.5%	MIL-STD-26E
High Temperature Storage	170°C for 1000hours, No power	≤±1%	IEC6011501-4.25
Bias Humidity	+85°C, 85% RH, 10%bias, 1000hours	≤±0.5%	MIL-STD-202 Method103
Mechanical shock	Condition C ,100 g's ,6 msec, 3 mutually perpendicular axes, in 6 directions, three impacts each for a total of 18 times 18 shocks.	≤±0.5%	MIL-STD-202 Method 213
Solderability	245±5°C, 2±0.5sec	At least 95% of surface area of electrode shall be covered with new solder	IEC60115-1-4.17 JIS-C5201-4.17
Operational life	70°C± 2°C, 1000 hours, at rated power 1.5 hours "ON", 0.5 hours "OFF"	≤±1%	MIL-STD-202 Method 108
Insulation Resistance	100V DC for 1 minute	>100 MΩ	IEC60115-1-4.6 JIS-C5201-4.6

Tapping & Package



	Pack	A	B	D0	E	F	P0	P1	P2	W	D1	T
		±0.2	±0.2	+0.5-0	±0.1	±0.05	±0.1	±0.1	±0.1	±0.2	±0.05	±0.15
2512	Emboss	3.60	6.90	1.50	1.75	5.50	4.00	4.00	2.00	12.00	1.50	1.20

Reel Specification



Type	A	B	C	D	M	W
2512	2.00±0.5	13.50±0.5	21.00±0.5	80.00±1.0	178.00±2.0	13.80±0.5

Packaging

Quantity: 4, 000pcs
 8mm wide tape on 178mm(7 inch)
 diameter reel -specification EIA
 Standard 481.

